

Rad Hard 1.5 Amp Three Terminal Adjustable Voltage Regulator

Description

The RAD HARD SGR117A 3-terminal positive adjustable regulators have been designed to meet the most stringent space and strategic level radiation requirements while meeting the industry standard LM117A and LM117 electrical specifications.

In addition to the features of the standard SGR117A, these devices are capable of meeting the attached data sheet electricals after the following radiation events:

TOTAL DOSE.....300 k RAD
 NEUTRON FLUENCE..... 5×10^{12} N/cm²

Features

- Full Electrical Performance After Radiation
 Exposure 300 k Rad Total Dose 5×10^{12} N/cm²
- 1% Output Voltage Tolerance
- 0.01%/V Line Regulation
- 0.3% Load Regulation
- Min. 1.5 A Output Current
- Available in TO-257 Package (Hermetic TO-220)

High Reliability Features

- Available to MIL-STD-883, ¶ 1.2.1
- Radiation Data Available
- MSC-AMS level "S" Processing Available

Block Diagram

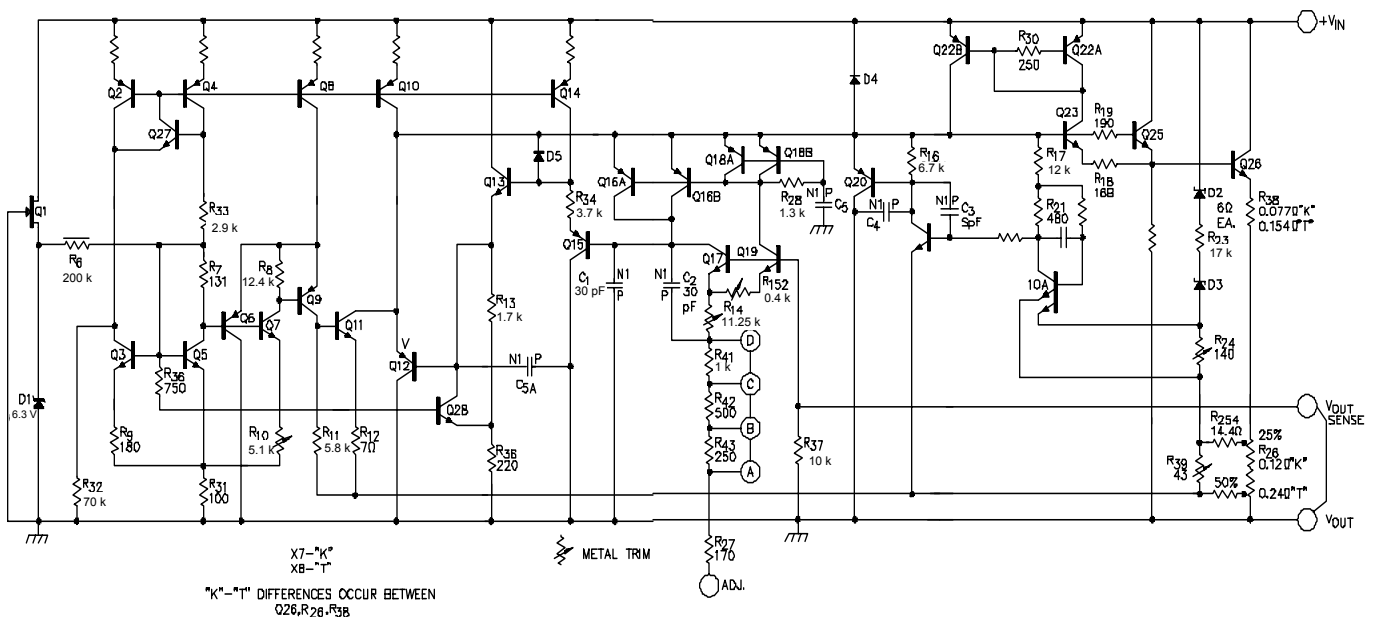


Figure 1 · Block Diagram

Absolute Maximum Ratings (Note 1)

Power Dissipation Internally Limited
 Input to Output Voltage Differential40 V
 Storage Temperature Range -65°C to 150°C

Operating Junction Temperature
 Hermetic (K, T, IG-Packages)150°C
 Lead Temperature (Soldering, 10 Seconds)300°C

Note 1. Exceeding these ratings could cause damage to the device.

Thermal Data

K Package:

Thermal Resistance-Junction to Case, θ_{JC} 3.0°C/W
 Thermal Resistance-Junction to Ambient, θ_{JA} 35°C/W

T Package:

Thermal Resistance-Junction to Case, θ_{JC} 15°C/W
 Thermal Resistance-Junction to Ambient, θ_{JA} 120°C/W

IG Package:

Thermal Resistance-Junction to Case, θ_{JC} 3.5°C/W
 Thermal Resistance-Junction to Ambient, θ_{JA} 42°C/W

Note A. Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$.

Note B. The above numbers for θ_{JC} are maximums for the limiting thermal resistance of the package in a standard mounting configuration. The θ_{JA} numbers are meant to be guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.

Recommended Operating Conditions (Note 2 & 3)

Input Voltage Range ($V_{OUT} + 3.5 V$) to 37 V

Operating Junction Temperature Range

SGR117A-55°C to 150°C

Note 2. Range over which the device is functional.

Note 3. These ratings are applicable for junction temperatures of less than 150°C.

Electrical Characteristics

(Unless otherwise specified, these specifications apply over full operating ambient temperatures for SGR117A with $-55^\circ\text{C} \leq T_A \leq 125^\circ\text{C}$, $V_{IN} - V_{OUT} = 5.0 V$, and for $I_{OUT} = 500 \text{ mA}$ (K and IG), and $I_{OUT} = 100 \text{ mA}$ (T package). Although power dissipation is internally limited, these specifications are applicable for power dissipations of 2 W for the T package, and 20 W for the K and IG packages. I_{MAX} is 1.5 A for the K and IG packages and 500 mA for the T package. Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.)

Parameter	Test Conditions	PRE RAD			POST NEUTRON			Units
		SGR117A			SGR117A			
		Min.	Typ.	Max.	Min.	Typ.	Max.	
Reference Voltage	$I_{OUT} = 10 \text{ mA}$, $T_A = 25^\circ\text{C}$ $3 V \leq (V_{IN} - V_{OUT}) \leq 40 V$, $P \leq P_{MAX}$	1.238	1.250	1.262	1.220		1.275	V
	$10 \text{ mA} \leq I_{OUT} \leq I_{MAX}$	1.225	1.250	1.270	1.220	1.25	1.275	V
Line Regulation (Note 4)	$3 V \leq (V_{IN} - V_{OUT}) \leq 40 V$, $I_L = 10 \text{ mA}$ $T_A = 25^\circ\text{C}$		0.005	0.01		0.01	0.03	%/V
	$T_A = T_{MIN}$ to T_{MAX}		0.01	0.02		0.02	0.05	%/V
Load Regulation (Note 4)	$10 \text{ mA} \leq I_{OUT} \leq I_{MAX}$ $V_{OUT} \leq 5 V$, $T_A = 25^\circ\text{C}$		5	15		5	50	mV
	$V_{OUT} \geq 5 V$, $T_A = 25^\circ\text{C}$		0.1	0.3		0.1	1	%
	$V_{OUT} \leq 5 V$		20	50		20	50	mV
	$V_{OUT} \geq 5 V$		0.3	1		0.3	1	%
Thermal Regulation (Note 5)	$T_A = 25^\circ\text{C}$, 20 ms pulse		0.002	0.02		0.03	0.07	%/W
Ripple Rejection	$V_{OUT} = 10 V$, $f = 120 \text{ Hz}$ $C_{ADJ} = 1 \mu\text{F}$, $T_A = 25^\circ\text{C}$		65			65		dB
	$C_{ADJ} = 10 \mu\text{F}$	66	80		66	80		dB
Adjust Pin Current			50	100		50	100	μA
Adjust Pin Current Change	$10 \text{ mA} \leq I_{OUT} \leq I_{MAX}$, $2.5 V \leq (V_{IN} - V_{OUT}) \leq 40 V$		0.2	5		0.2	8	μA

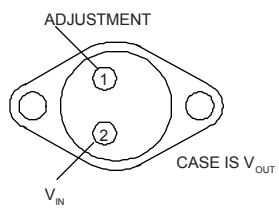
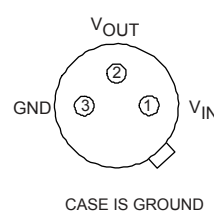
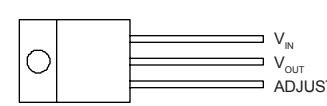
Electrical Characteristics (Continued)

Parameter	Test Conditions	PRE RAD			POST NEUTRON			Units
		SGR117A			SGR117A			
		Min.	Typ.	Max.	Min.	Typ.	Max.	
Minimum Load Current	$(V_{IN} - V_{OUT}) = 40\text{ V}$		3.5	5		3.5	8	mA
Current Limit	$(V_{IN} - V_{OUT}) \leq 15\text{ V}$							
	K, IG Packages	1.5	2.2		1.5	2.2		A
	T Package	0.5	0.8		0.5	0.8		A
	$(V_{IN} - V_{OUT}) = 40\text{ V}, T_J = 25^\circ\text{C}$							
	K, IG Packages	0.3	0.4		0.3	0.4		A
	T Package	0.15	0.2		0.15	0.2		A
Temperature Stability (Note 5)			1	2				%
Long Term Stability (Note 5)	$T_A = 125^\circ\text{C}, 1000\text{ Hours}$		0.3	1				%
RMS Output Noise (% of V_{OUT})	$T_A = 25^\circ\text{C}, 10\text{ Hz} \leq f \leq 10\text{ kHz}$ (Note 5)		0.001					%

Note 4. Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output voltage due to heating effects are covered under the specification for thermal regulation.

Note 5. These parameters, although guaranteed, are not tested in production.

Connection Diagrams and Ordering Information (See Notes Below)

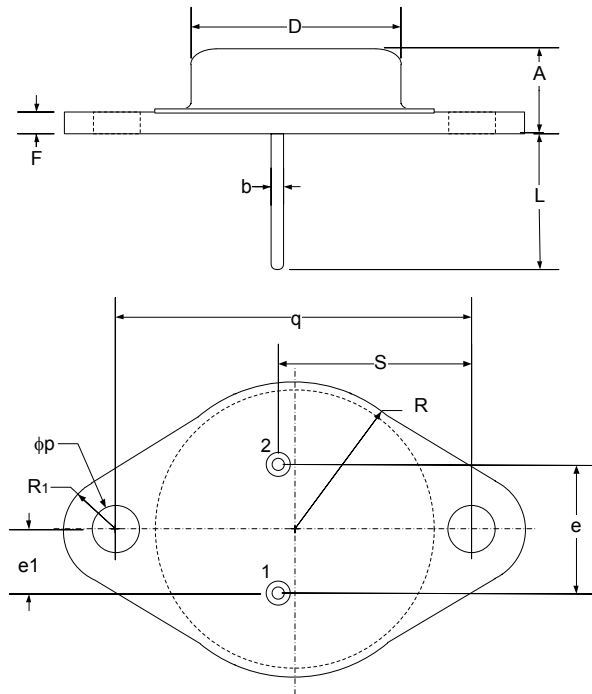
Package	Part No.	Ambient Temperature Range	Connection Diagram
3-TERMINAL TO-3 METAL CAN K-PACKAGE	SGR117AK SGR117AK-883B	-55°C to 125°C -55°C to 125°C	
3-PIN TO-39 METAL CAN T-PACKAGE	SGR117AT SGR117AT-883B	-55°C to 125°C -55°C to 125°C	
3-PIN HERMETIC TO-257 IG-PACKAGE (Isolated)	SGR117AIG-883B SGR117AIG	-55°C to 125°C -55°C to 125°C	

Note 1. Device leads are hot solder dipped with Sn63Pb37 solder.

Note 2. All parts are viewed from the top.

Package Outline Dimensions

Controlling dimensions are in inches, metric equivalents are shown for general information.

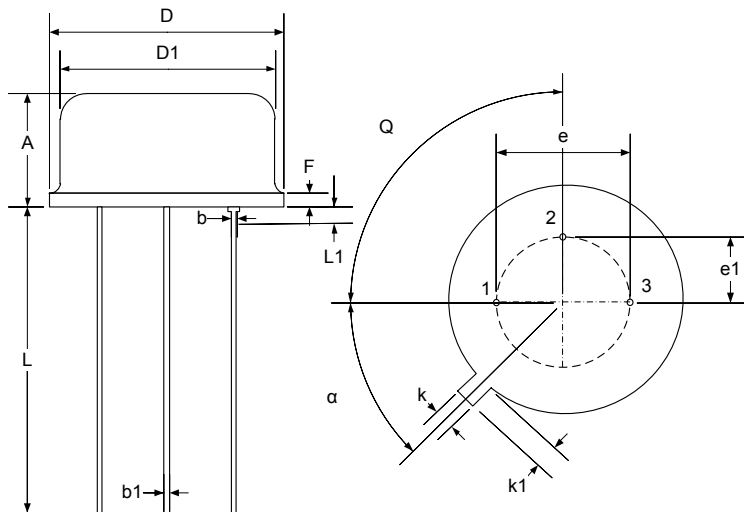


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.86	7.62	0.270	0.300
q	29.90	30.40	1.177	1.197
b	0.97	1.09	0.038	0.043
D	19.43	19.68	0.765	0.775
S	16.64	17.14	0.655	0.675
e	10.67	11.18	0.420	0.440
e1	5.21	5.72	0.205	0.225
F	1.52	2.03	0.060	0.080
ϕ_p	3.84	4.09	0.151	0.161
L	10.79	12.19	0.425	0.480
R1	3.33	4.78	0.131	0.188
R	12.57	13.34	0.495	0.525

Note:

Dimensions do not include protrusions; these shall not exceed 0.155mm (.006") on any side. Lead dimension shall not include solder coverage.

Figure 2 · K 3-Pin Metal Can TO-3 Package Dimensions



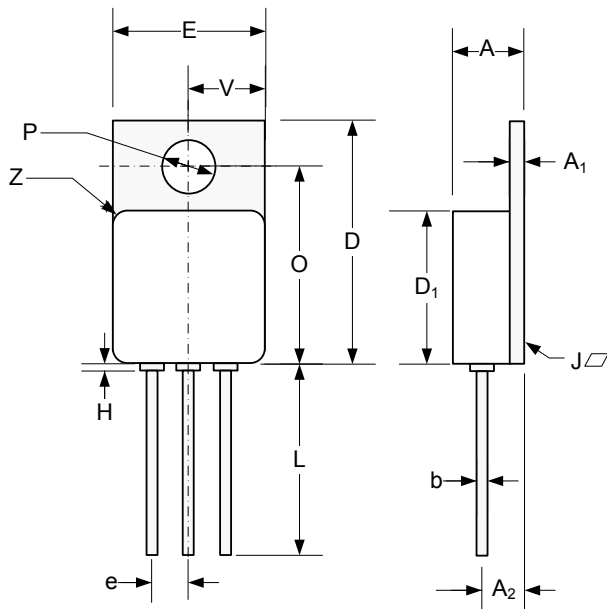
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.19	4.70	0.165	0.185
b	0.41	0.48	0.016	0.019
b1	0.41	0.53	0.016	0.021
D	8.89	9.40	0.350	0.370
D1	8.13	8.51	0.320	0.335
e	5.08 BSC		0.200 BSC	
e1	2.54 TYP		0.100 TYP	
F	-	1.02	-	0.040
k	0.71	0.86	0.028	0.034
k1	0.74	1.14	0.029	0.045
L	12.70	14.48	0.500	0.570
L1	-	1.27	-	0.050
Q	90° TYP		90° TYP	
α	45° TYP		45° TYP	

Note:

Dimensions do not include protrusions; these shall not exceed 0.155mm (.006") on any side. Lead dimension shall not include solder coverage.

Figure 3 · T 3-Pin Metal Can TO-39 Package Dimensions

Package Outline Dimensions (continued)



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.70	5.21	0.185	0.205
A ₁	0.89	1.14	0.035	0.045
A ₂	2.92	3.18	0.115	0.125
b	0.71	.081	0.027	0.032
D	16.38	16.76	0.645	0.660
D ₁ *	10.41	10.92	0.410	0.430
e	2.54 BSC		0.100 BSC	
E*	10.41	10.67	0.410	0.420
H	-	0.50	-	0.020
L	12.70	-	0.500	-
O	13.39	13.64	0.527	0.537
P	3.56	3.81	0.140	0.150
J	-	0.10	-	0.004
V	5.13	5.38	0.202	0.212
Z	1.40 TYP		0.055 TYP	

*Excludes Weld Fillet Around Lid.

Note:

Dimensions do not include protrusions; these shall not exceed 0.155mm (.006") on any side. Lead dimension shall not include solder coverage.

Figure 4 · IG 3-Pin Hermetic TO-257 Package Dimensions



Microsemi Corporate Headquarters
One Enterprise, Aliso Viejo,
CA 92656 USA

Within the USA: +1 (800) 713-4113
Outside the USA: +1 (949) 380-6100
Sales: +1 (949) 380-6136
Fax: +1 (949) 215-4996

E-mail: sales.support@microsemi.com

© 2015 Microsemi Corporation. All rights reserved. Microsemi and the Microsemi logo are trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners.

Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for communications, defense & security, aerospace and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; security technologies and scalable anti-tamper products; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, Calif., and has approximately 3,400 employees globally. Learn more at www.microsemi.com.

Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever arising out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or parameters provided by Microsemi. It is the Buyer's responsibility to independently determine suitability of any products and to test and verify the same. The information provided by Microsemi hereunder is provided "as is, where is" and with all faults, and the entire risk associated with such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other IP rights, whether with regard to such information itself or anything described by such information. Information provided in this document is proprietary to Microsemi, and Microsemi reserves the right to make any changes to the information in this document or to any products and services at any time without notice.